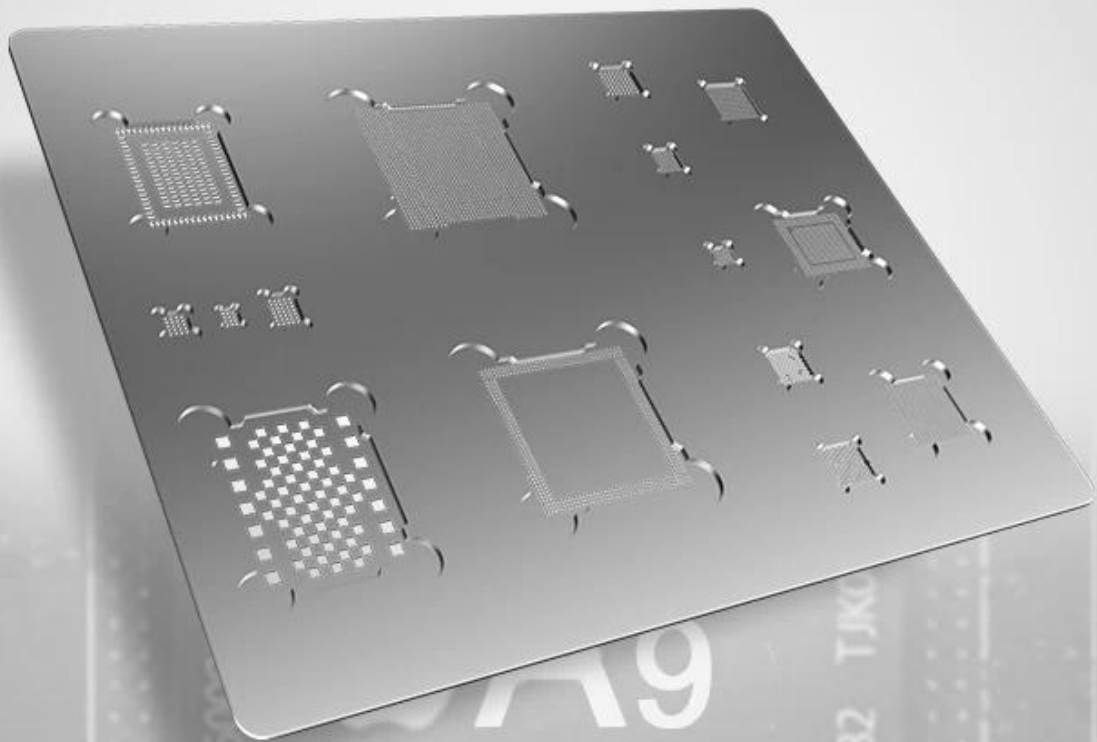


**BEST-A9- BGA IC Reballing iPhone 6 6P**

iPhone 6s Plus 1x BGA Reballing Stencils

iPhone 6s 1x BGA Reballing Stencils

# 3D GROOVE — REBALLING STENCIL —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

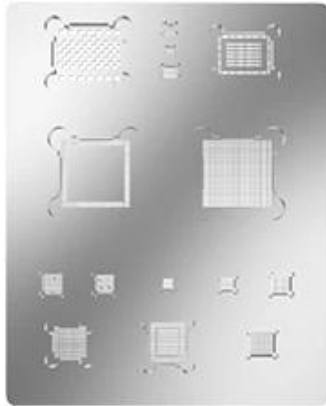


PRECISE ALIGNMENT



SQUARE HOLE

## Product Usage



MODEL	A9
WEIGHT	18.8g
MATERIAL	imported steel
SIZE	68.9 X 84.9mm
MATCHING MACHINE TYPE	iPhone6S/6SPlus

### ▼ CHARACTERISTICS

This product is used for BGA tinning repair of the iPhone 6S/6sPlus series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

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IMPORTED STEEL

HIGH TOUGHNESS



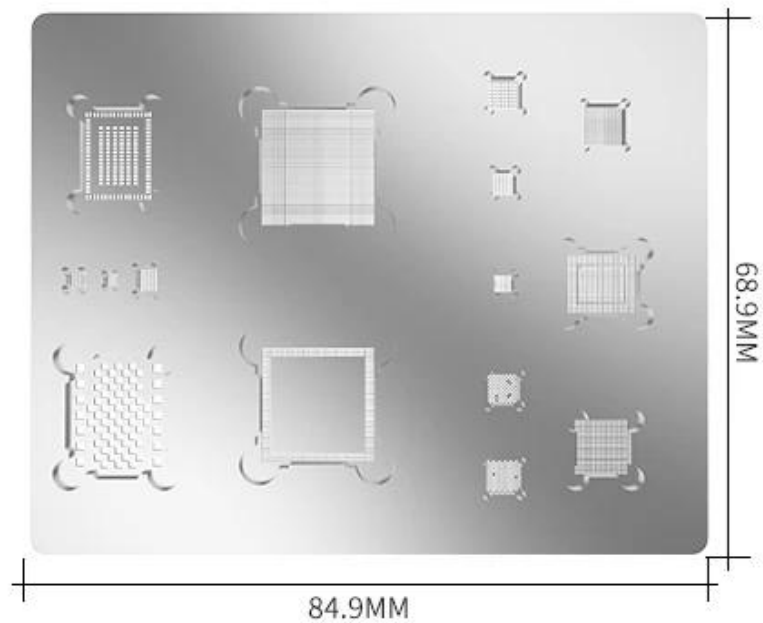
Easily mounted on the steel mesh to make the chip fit more closely with the mesh  
Therefore, the chip after tinning is "more precise"





Imported steel  
Hard and wear resistant  
Accurate to the hole

## PRODUCT SIZE



Thin to 0.31mm

Precise die-casting **form heating**



